

**AMENDMENTS TO THE CLAIMS:**

**Claims 1-14 (Canceled)**

15. **(Currently Amended)** A method for detachably attaching a device to a substructure, said method comprising the steps of:

- a) attaching a pair of rails to opposed sides of the device;
- b) slidably engaging the pair of rails with a pair of guides mounted on the substructure;
- c) aligning repositioning an alignment pin extending from one of the rails with a hole in one of the guides to align an electrical connector of the device with an electrical connector mounted on the substructure;
- d) securing a cross member interconnecting the pair of rails with a face plate attached to the substructure to secure the device with the substructure; and
- e) dissipating any attendant electrostatic charge upon execution of said step of sliding.

16. **(Original)** The method as set forth in Claim 15 wherein said step of dissipating includes the step of translating a spring extending from a rail along the corresponding one of the guides.

17. **(Currently Amended)** The method as set forth in Claim 15 [[16]] including the step of contacting a plate ~~secured in the guide~~ and extending from the substructure with a [[the]]

spring during execution of said step of translating.

**Claims 18-20 (Canceled)**

21. **(New)** The method as set forth in Claim 16 including the step of contacting a plate extending from the superstructure with the spring during extension of said step of translating.

22. **(New)** A method for detachably attaching a device to a substructure, said method comprising the steps of:

- a) attaching a pair of rails to opposed sides of the device;
- b) slidably engaging the pair of rails with a pair of guides mounted on the substructure;
- c) aligning an alignment pin extending from one of the rails with a hole in one of the guides to align an electrical connector of the device with an electrical connector mounted on the substructure; and
- d) dissipating any attendant electrostatic charge upon execution of said step of engaging.

23. **(New)** The method as set forth in Claim 22 wherein said step of dissipating includes the step of translating a spring extending from a rail along the corresponding one of the guides.

24. **(New)** The method as set forth in Claim 22 including the step of contacting a plate

extending from the substructure with a spring during execution of said step of translating.

25. (New) The method as set forth in Claim 22 including the step of contacting a plate extending from the superstructure with the spring during extension of said step of translating.

26. (New) A method for detachably attaching a device to a substructure, said method comprising the steps of:

- a) attaching a pair of rails to opposed sides of the device;
- b) slidably engaging the pair of rails with a pair of guides mounted on the substructure;
- c) securing a cross member interconnecting the pair of rails with a face plate attached to the substructure to secure the device with the substructure; and
- d) dissipating any attendant electrostatic charge upon execution of said step of engaging.

27. (New) The method as set forth in Claim 26 wherein said step of dissipating includes the step of translating a spring extending from a rail along the corresponding one of the guides.

28. (New) The method as set forth in Claim 26 including the step of contacting a plate extending from the substructure with a spring during execution of said step of translating.

29. (New) The method as set forth in Claim 27 including the step of contacting a plate

extending from the superstructure with the spring during extension of said step of translating.